



ISO-9001-2008 Certified

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TECHNICAL BULLETIN

TGF-331 THERMALLY CONDUCTIVE GAP FILLER

TGF-331 is a high temperature resistant, liquid gap filler with very high thermal conductivity. It is a heavily filled system with heat conductive metal oxides. The material is a two-component, cured either at room or elevated temperature. The material is an excellent solution for interfacing fragile components.

TYPICAL PROPERTIES:

Color	Light Blue
Specific Gravity	2.6
Operating Temperature Range	-40°C to 205°C
Thermal Conductivity @ 36°C W/m.°K	3.6
Thermal Resistance, °C-in ² /W	0.05
Dielectric Strength (0.05" gap), Volts/mil	275
Dielectric Constant, 1 kHz	8.0
Dissipation Factor, 1 kHz	0.003
Volume Resistivity, ohm-cm	1.1x10 ¹⁰
Mix Ratio, by volume	1:1
Mix Ratio, by weight	1:1
Mixed Viscosity, cPs	100,000 -150,000
Shelf Life, @ 25°C	6 months
Cure Schedule	30 minutes @ 100°C 24 hrs @ 25°C

FOR INDUSTRIAL USE ONLY:

These materials are intended for industrial use only, and the practices of good housekeeping, safety and cleanliness should be followed before, during and after use.

WARNING!

Although the system contains low volatility materials, care should be taken in handling. Adequate ventilation of work place and ovens is essential. In case of skin contact, wash thoroughly with soap and water. For eyes, flush immediately with plenty of water for at least 10 minutes and seek medical attention. Refer to Material Safety Data Sheet for additional health and safety information.

SHELF LIFE:

The shelf life of these materials is 6 months from the date of manufacture when stored in unopened containers at an average temperature of 25°C.

DISCLAIMER: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performance. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not to be construed as recommendations to infringe any patent.